

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC0500NSI	**Issued**	08. April 2022
MA#	MA005710523		
Package	PG-TDSON-8-6	**Weight***	115.93 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	0.54	0.54	5427	5427
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		424	
	non noble metal	copper	7440-50-8	49.082	42.35	42.40	423392	423943
wire	non noble metal	copper	7440-50-8	0.021	0.02	0.02	180	180
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		712	
	plastics	epoxy resin	-	5.858	5.05		50534	
	inorganic material	silicondioxide	60676-86-0	35.314	30.46	35.58	304629	355875
leadfinish	non noble metal	tin	7440-31-5	1.452	1.25	1.25	12522	12522
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1428	1428
solder	non noble metal	tin	7440-31-5	0.019	0.02		162	
	noble metal	silver	7440-22-4	0.023	0.02		202	
	non noble metal	lead	7439-92-1	0.895	0.77	0.81	7717	8081
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		58	
	non noble metal	iron	7439-89-6	0.022	0.02		193	
	non noble metal	copper	7440-50-8	22.292	19.23	19.26	192293	192544
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com